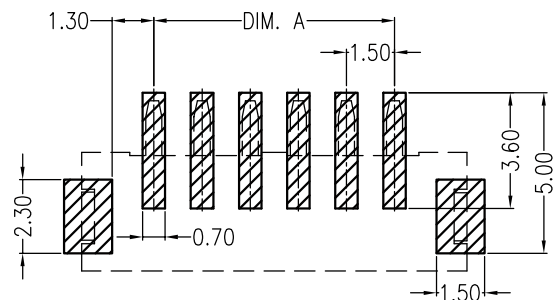


Assembly Layout

主要技术参数 Main Specifications

- 线数 (Poles): 02 to 16
- 接触电阻 (Contact resistance):  $\leq 20\text{m}\Omega$
- 绝缘电阻 (Insulation resistance):  $\geq 500\text{M}\Omega$
- 额定电压 (Rated voltage): 125V AC DC
- 额定电流 (Rated current): 1.0A AC DC
- 耐电压 (Withstand Voltage): 500V AC/minute
- 温度范围 (Temperature Range):  $-25^{\circ}\text{C} \sim +105^{\circ}\text{C}$



SUGGESTED PCB LAYOUT

Circuits	Dimensions (mm)		
	DIM. A	DIM. B	DIM. C
02	1.50	3.60	6.00
03	3.00	5.10	7.50
04	4.50	6.60	9.00
05	6.00	8.10	10.50
06	7.50	9.60	12.00
07	9.00	11.10	13.50
08	10.50	12.60	15.00
09	12.00	14.10	16.50
10	13.50	15.60	18.00
11	15.00	17.10	19.50
12	16.50	18.60	21.00
13	18.00	20.10	22.50
14	19.50	21.60	24.00
15	21.00	23.10	25.50
16	22.50	24.60	27.00

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	SOLDER TAB	2 PCS	PhosphorBronze	Sn-plated/Au
B	CONTACT	2~16 PCS	Brass	Sn-plated/Au
A	PEDESTAL	1 PCS	LCP/PA9T	UL 94V-0, COLOR:BEIGE

LEDsconn			TITLE: 1.5mmPITCH 180°WAFER SMT TYPE		
X.±0.5	X.±5'	USE: CUSTOMER	PART NO.:		
.X±0.3	.X±2'				
.XX±0.25	.XX±1'	APPD: 邵敬和	DWG NO.:		
--	--	CHKD: 田峰			
⊕	△	UNITS: mm	DR: 蒋建银	SCALE 1 : 1	SHEET 1 / 1

REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	吴丹平	2016.05.05
A1		增加PA9T材料、镀金镀层	周秀龙	2017.10.09
A2		设变吸取盖	蒋建银	2018.05.04